



2019 WSC  
世界半导体大会  
创新协作 世界同“芯”



SOI PLATFORMS FOR AUTOMOTIVE, IOT, 5G, AI/EDGE COMPUTING  
NANJING, 302 HALL, FROM 13:00 TO 16:30

SOI平台之于汽车、物联网、5G、AI/边缘计算  
南京302厅，13:00-16:30

*2019 WSC Nanjing - Nanjing 302 Hall*

## **SOI Platforms for Automotive, IoT, 5G, AI/Edge Computing**

### **Session 1: Applications**

- 13:00 – 13:05 Opening remarks; Carlos Mazure, Chairman, SOI Industry Consortium
- 13:05 – 13:30 “The Perspective of China SOI Ecosystem”, Jeffrey Wang, CEO, Simgui
- 13:30 – 13:55 “SOI platforms for automotive, IoT, 5G”; Jian Zhang, VP, NXP
- 13:55 – 14:15 “RF-SOI ecosystem”; Mostafa Emam, CEO, Incize
- 14:15 – 14:35 “Automotive SOI with embedded PCRAM”; Giorgio Cesana, Sr. Director, STMicroelectronics

***14:35 – 14:55 Break***

### **Session 2: EDA/IP infrastructure and innovation**

- 14:55 – 15:15 “Design transparency with FD-SOI”; Christophe Tretz, IBM & Design Expert, SOI Industry Consortium
- 15:15 – 15:35 “FDSOI Foundry Enablement – From Concept to Mass Production”, Mao Liu, Product Manager, Cadence
- 15:35 – 15:55 “Mixed signal computing with FD-SOI for AIoT”; Hongjie Liu, CEO, Reexen
- 15:55 – 16:15 “EDA Enablement for RF- and FD-SOI”; Feng Ling, CEO, Xpedic
- 16:15 – 16:30 “SOI EDA/IP Overview”; Jon Cheek, Executive Director, SOI Industry Consortium

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### **SOI平台之于汽车、物联网、5G、AI/边缘计算**

#### **第一场：应用**

- 13:00 – 13:05 开场致辞；SOI国际产业联盟主席 Carlos Mazure
- 13:05 – 13:30 “中国SOI生态系统概览”，新傲科技执行总裁 王庆宇

13:30 – 13:55 “从汽车、物联网和5G看SOI平台，恩智浦半导体副总裁 张坚

13:55 – 14:15 “RF-SOI生态系统”，INCIZE执行总裁 Mostafa Emam

14:15 – 14:35 “汽车SOI：嵌入式PCRAM”，意法半导体战略部资深总监 Giorgio Cesana

**14:35 – 14:55 休息**

## **第二场：EDA/IP基础架构和创新**

14:55 – 15:15 “FD-SOI让设计更透明”，IBM和SOI国际产业联盟设计专家 Christophe Tretz

15:15 – 15:35 “Cadence的SOI世界”，Cadence全球副总裁兼南京凯鼎电子科技CEO 王琦

15:35 – 15:55 FDSOI Foundry Enablement – From Concept to Mass Production”, Mao Liu, Product Manager, Cadence

15:55 – 16:15 “EDA助力RF-SOI和FD-SOI”，芯禾科技CEO 凌峰

16:15 – 16:30 “SOI产业EDA/IP概览”，SOI国际产业联盟执行董事 Jon Cheek